

April 22, 2014

**PCN Number:** PCN1402

**PCN Change Level:** Minor

**Subject:** Hot Solder Dip Supplier Added for FPGA Products in CQFP and CPGA Packages

Dear Microsemi Customer,

**Description of Change:** “ACE Production Technologies” has been added as a supplier for the hot solder dip and solderability service for Ceramic Quad Flat Pack (CQFP) and Ceramic Pin Grid Array (CPGA) FPGA packages ordered with hot solder dip finish. This change does not apply to Ceramic Column Grid Array (CCGA) packages.

**Reason for Change:** Existing hot solder dip supplier “Premier Semiconductor Services” was acquired by “Micros Components”. As part of consolidation, Premier’s existing facility in Arizona is being closed (used for processing our products).

**Application Impact:** There is no change to the solder coating composition, form, fit, function, quality, reliability or performance of the product.

**Method of Identifying Changed Product:** Product processed for hot solder dip service at “ACE Production Technologies” is electronically traceable, based on customer purchase or sales order.

**Products Affected by this Change:** Refer to “Addendum A” (at the end of this notice) for a complete part number list.

**Production Shipment Schedule:** This change is effective immediately; “ACE Production Technologies” has been successfully qualified for hot solder dip and solderability.

**Qualification Data:** Qualification was successfully completed per requirements of MIL-PRF-38535 with regards to (1) Solder depth and thickness (2) External visual per MIL-STD-883 TM2009 and (3) Solderability test per MIL-STD-883 TM2003 and J-STD-002. Qualification data and results of on-site assessment can be provided upon request.

**Contact Information:** Microsemi SoC Products Group

If you have any questions related to this topic, contact Microsemi's Technical Support at:  
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Regards,

Microsemi

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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**Table 1 • Addendum A**

<b>SMD Part Number</b>	<b>Cross Reference to Microsemi FPGA Part Number</b>
5962-9215601MXA	A1280A-PG176B
5962-9215601MYA	A1280A-CQ172B
5962-9215602MXA	A1280A-1PG176B
5962-9215602MYA	A1280A-1CQ172B
5962-9322101MXA	A1240A-PG132B
5962-9322102MXA	A1240A-1PG132B
5962-9096403MXA	A1010B-PG84B
5962-9096404MXA	A1010B-1PG84B
5962-9096503MTA	A1020B-CQ84B
5962-9096503MUA	A1020B-PG84B
5962-9096504MTA	A1020B-1CQ84B
5962-9096504MUA	A1020B-1PG84B
<b>Note:</b> Also impacts all FPGA ceramic QFP and PGA package part numbers ending with the following special order suffixes: X13, X15, X19, X20, X27, X70, X81, X96, X182, X370 & X394.	